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FOR IMMEDIATE RELEASE

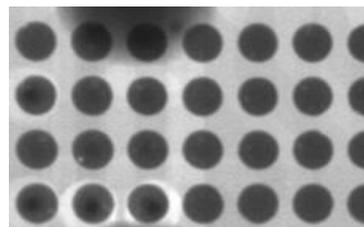
Press Release

YINCAE's Fully Flux Residue Compatible Underfill: UF 158HA

(Albany, NY) **August 15, 2022** YINCAE is excited to announce that we have developed UF 158HA that is fully compatible with flux residue and high performance underfill. Using UF 158HA can eliminate cleaning process and pollution from the cleaning process, and simplify the manufacturing process.

Due to its unique properties, UF 158HA is not only a high performance underfill but also can function as solder mask with eliminating electric migration. The benefits of using UF 158HA are:

- Fully compatible with all no-clean solder paste flux residue
- Eliminating cleaning process and its pollution
- Large cost saving
- Pass 5x260 °C without any deformation of solder joint
- Better than all competitors' underfill with cleaning process
- Be able to flow into 20µ gap
- Withstand high temperature up to 400 °C.



After 5X260°C Reflow

This material can be used for BGA, flip chip, wafer-level chip scale package application. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules. It is designed for high production and friendly environment where process speed, mechanical shock and reliability are key concerns.

For more information on YINCAE's UF 158HA underfill, or to learn more about the YINCAE product range, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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